

General Description

The Sanrise SRT10N070H is a low voltage power MOSFET, fabricated using advanced split gate trench technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and synchronous rectification.

The SRT10N070H break down voltage is 100V and it has a high rugged avalanche characteristics. The SRT10N070H is available in PDFN5*6 and TO-220C packages.

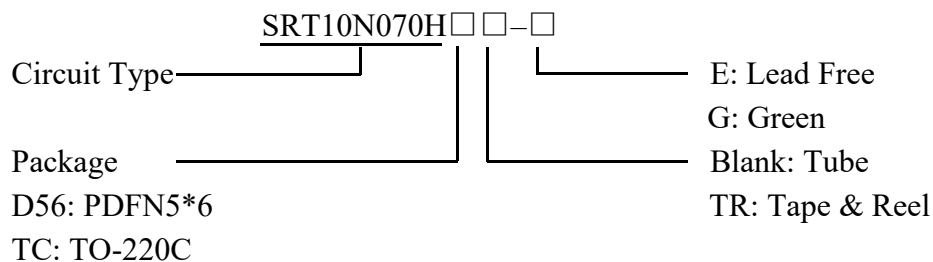
Features

- Ultra Low
- $R_{DS(ON_TYP)} = 5.7m\Omega$,PDFN5*6 @ $V_{GS} = 10V$.
- $R_{DS(ON_TYP)} = 6.3m\Omega$,TO-220C @ $V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g=32.1nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

Application

- Charger / Adapter
- Server/Telecom
- High Power Supply
- E-Tools

Ordering Information



Package	Part Number		Marking ID		Packing Type
	Lead Free	Green	Lead Free	Green	
PDFN5*6	SRT10N070HD56TR-E	SRT10N070HD56TR-G	SRT10N070HD56E	SRT10N070HD56G	Tape & Reel
TO-220C	SRT10N070HTC-E	SRT10N070HTC-G	SRT10N070HTCE	SRT10N070HTCG	Tube

Symbol

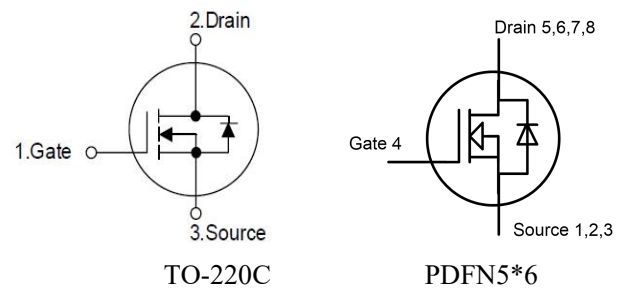


Figure 1 Symbol of SRT10N070H

Package Type

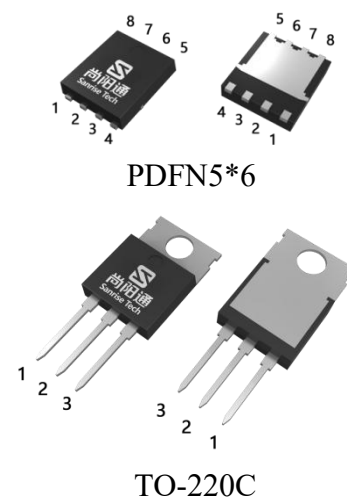


Figure 2 Package Type of SRT10N070H

Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit	
Drain-Source Voltage		V_{DSS}	100	V	
Gate-Source Voltage		V_{GSS}	±20	V	
Continuous Drain Current	$T_C=25^{\circ}C$	I_D	PDFN5*6	84	A
			TO-220C	87	
	$T_C=100^{\circ}C$		PDFN5*6	53	
			TO-220C	56	
Pulsed Drain Current (Note 2)		I_{DM}	336	A	
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	36	mJ	
Avalanche Destructive Energy, Single Pulse (Note 4)		E_{AS_Limit}	306	mJ	
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.05	mJ	
Avalanche Current, Repetitive (Note 2)		I_{AR}	12	A	
Continuous Diode Forward Current		I_S	84	A	
Diode Pulse Current		$I_{S,PULSE}$	320	A	
Max Power Dissipation		P_D	96.1	W	
Operating Junction Temperature		T_J	150	°C	
Storage Temperature		T_{STG}	-55 to 150	°C	
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	°C	

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS}=12.0A$, $V_{DD}=50V$, $R_G=25\Omega$, Starting $T_J=25^{\circ}C$
- $I_{AS_Limit}=35A$, $V_{DD}=50V$, $R_G=25\Omega$, Starting $T_J=25^{\circ}C$

Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	PDFN5*6	R_{thJC}			1.3	°C/W
Thermal Resistance, Junction-to-Ambient		R_{thJA}			50	°C/W
Thermal Resistance, Junction-to-Case	TO-220C	R_{thJC}			1.1	°C/W
Thermal Resistance, Junction-to-Ambient		R_{thJA}			60	°C/W

Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	2.0	3.0	4.0	V
Static Drain-Source On-Resistance	PDFN5*6	$R_{DS(ON)}, V_{GS}=10V, I_D=14A$		5.7	7.0	mΩ
	TO-220C			6.3	7.5	
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		1.7		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		2.1		nF
Output Capacitance	C_{OSS}			720		pF
Reverse Transfer Capacitance	C_{RSS}			13		pF
Effective output capacitance, energy related ^{NOTE5}	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 80V$		690		pF
Effective output capacitance, time related ^{NOTE6}	$C_{O(tr)}$			920		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V, I_D=30A, R_G=3.0\Omega, V_{GS}=10V$		10		nS
Rise Time	t_r			5		
Turn-off Delay Time	$t_{d(off)}$			22		
Fall Time	t_f			6		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=50V, I_D=30A, V_{GS}=0 \text{ to } 10.0V$		9.7		nC
Gate to Drain Charge	Q_{gd}			6.2		
Gate Charge Total	Q_g			32.1		
Gate Plateau Voltage	$V_{plateau}$			4.6		V
Gate Charge Total, sync FET	Q_g	$V_{DD}=0.1V, V_{GS}=0 \text{ to } 10V$		27.6		nC
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=30A$		0.85	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=50V, I_F=30A, dI_F/dt=100A/\mu s$		53		nS
Reverse Recovery Charge	Q_{rr}			93		nC
Peak Reverse Recovery Current	I_{rrm}			3.5		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 80V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 80 V

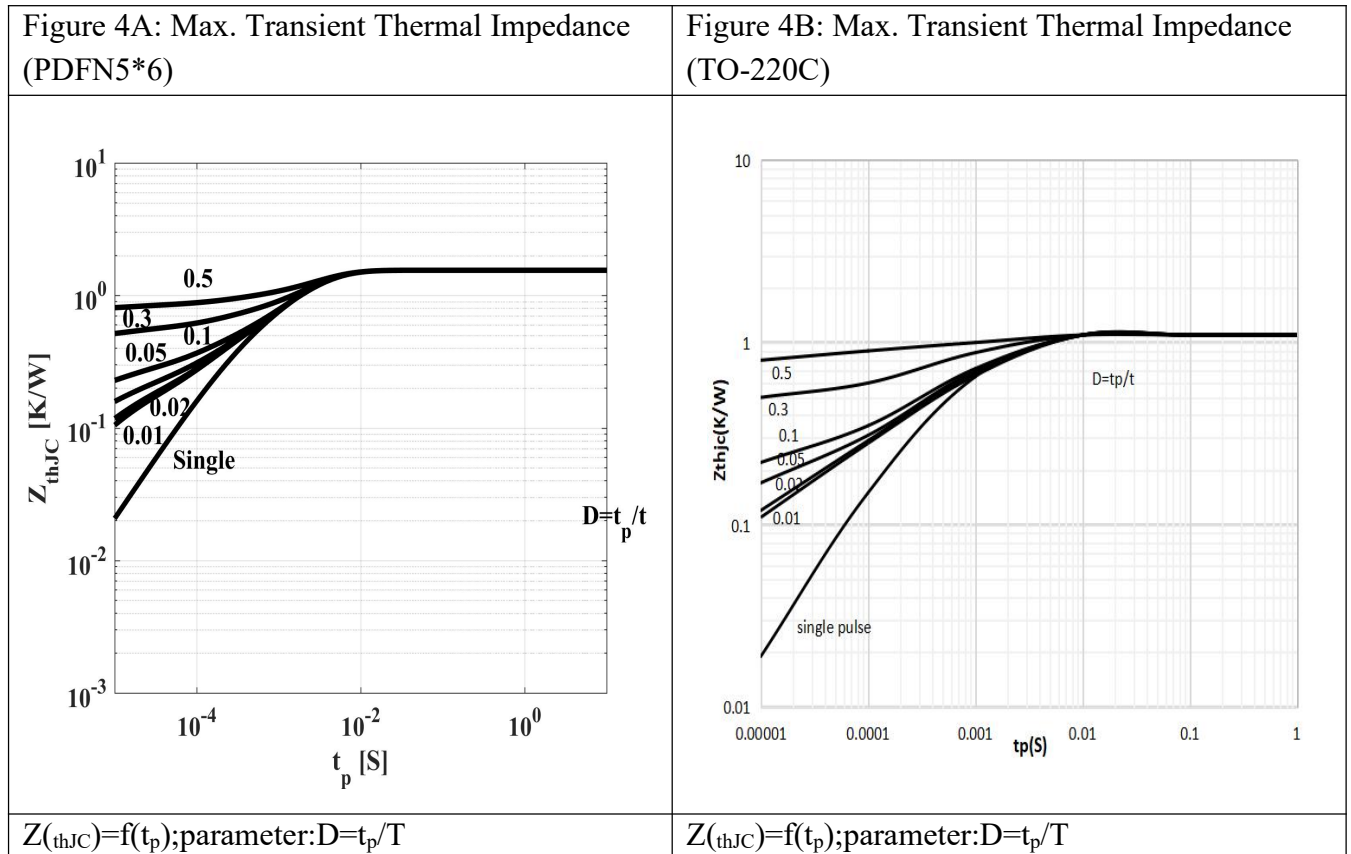
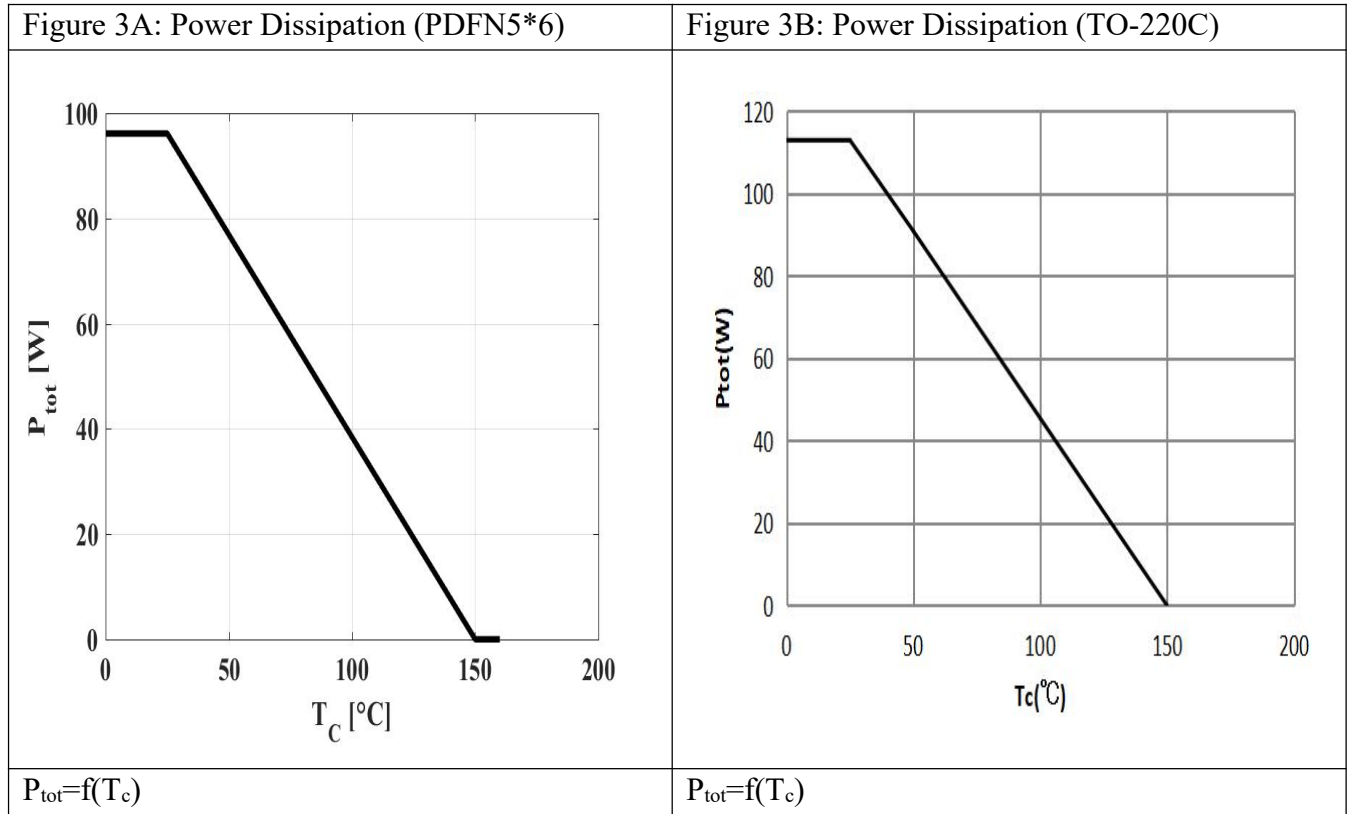
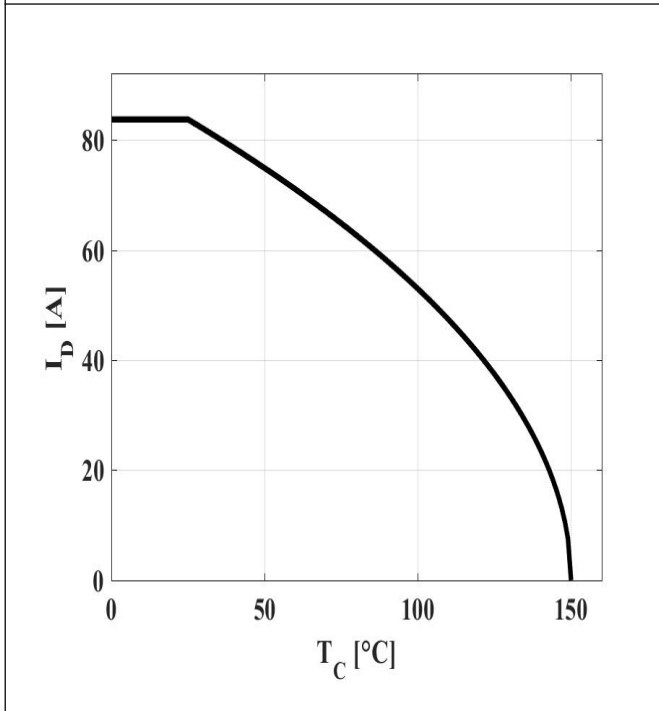
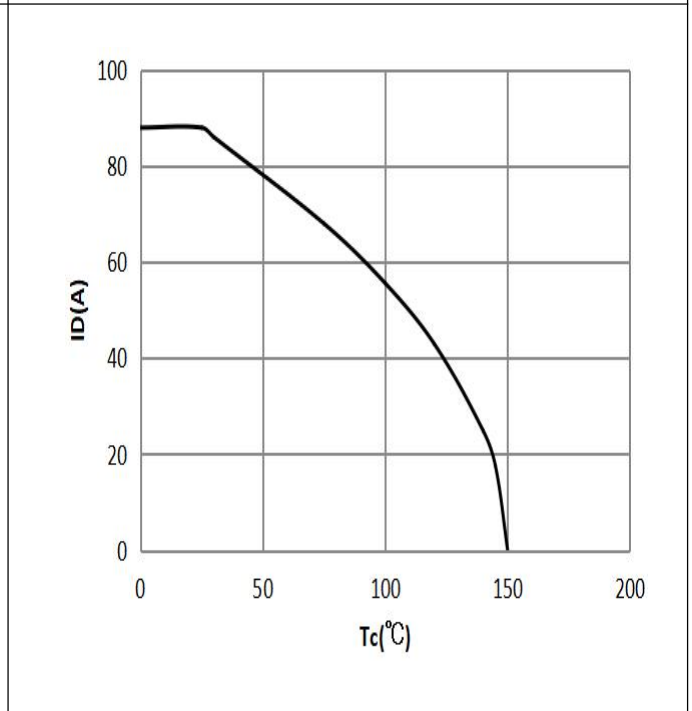
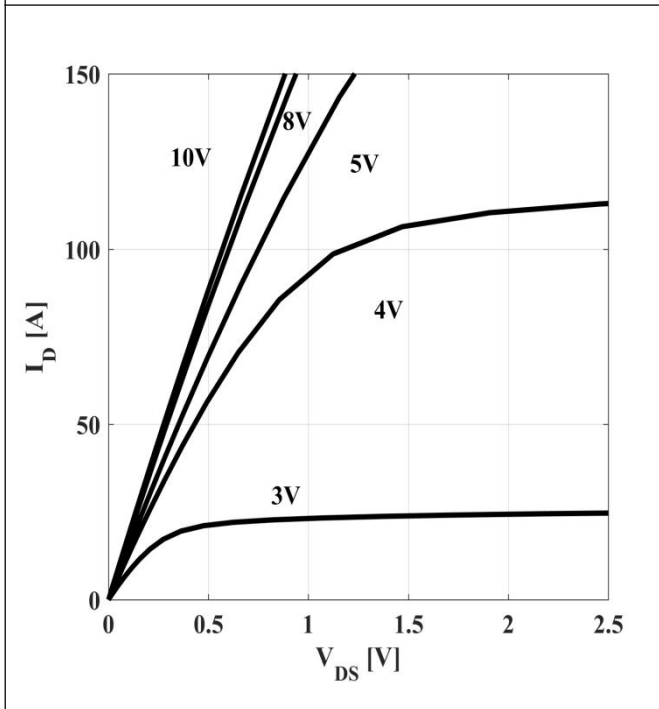
Typical Performance Characteristics


Figure5A: Drain Current(PDFN5*6)


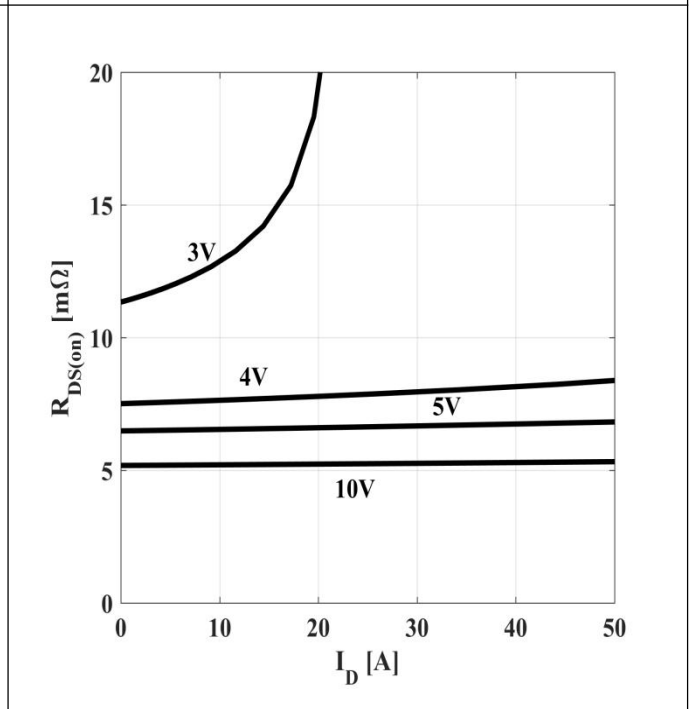
$$I_D=f(T_C);V_{GS}\geq 10V$$

Figure5B: Drain Current(TO-220C)


$$I_D=f(T_C);V_{GS}\geq 10V$$

Figure6: Typ. Output Characteristics


$$I_D=f(V_{DS});T_j=25^{\circ}C; \text{ parameter: } V_{GS}$$

Figure7: Typ. Drain-Source On-State Resistance


$$R_{DS(ON)}=f(I_D);T_j=25^{\circ}C; \text{ parameter: } V_{GS}$$

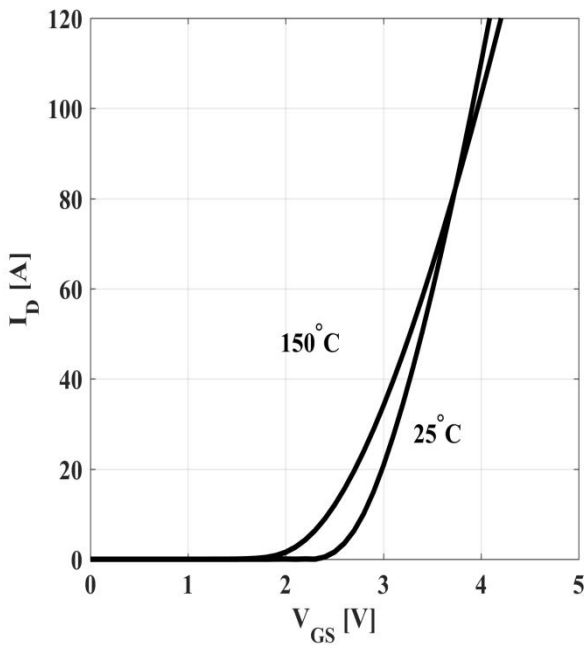
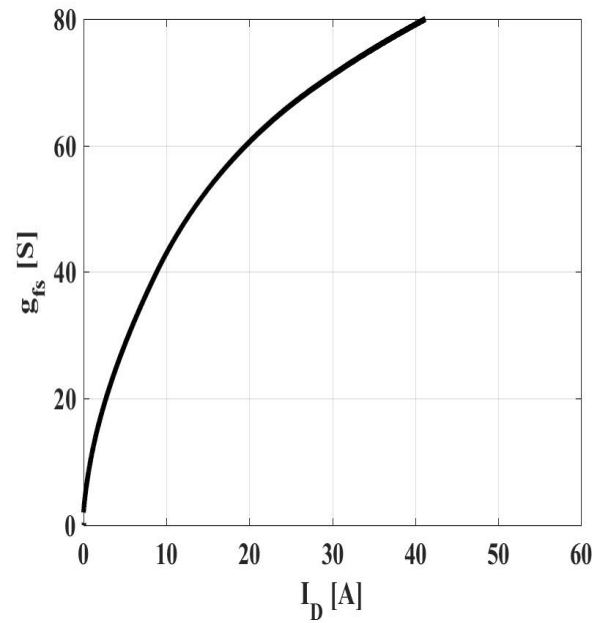
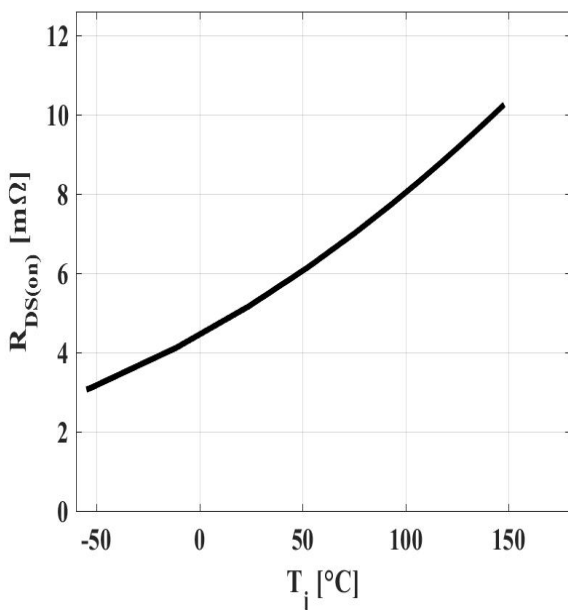
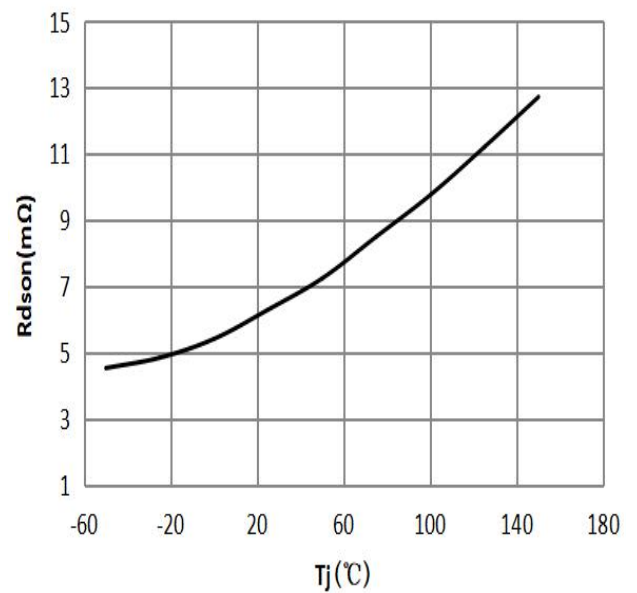
Figure8: Typ. Transfer Characteristics

 $I_D=f(V_{GS}); |V_{DS}|>2|I_D|R_{DS(on)max}; \text{parameter: } T_j$
Figure9: Typ. Forward Transconductance

 $g_{fs}=f(I_D); T_j=25^\circ\text{C}$
Figure10A: Typ. Drain-Source On-State Resistance(PDFN5*6)

 $R_{DS(ON)}=f(T_j); I_D=14\text{A}; V_{GS}=10\text{V}$
Figure10: Typ. Drain-Source On-State Resistance (TO-220C)

 $R_{DS(ON)}=f(T_j); I_D=14\text{A}; V_{GS}=10\text{V}$

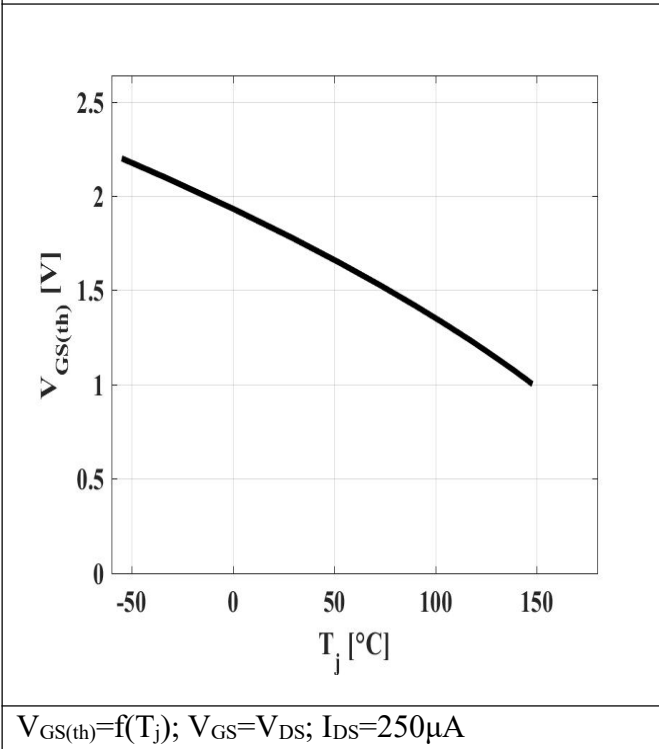
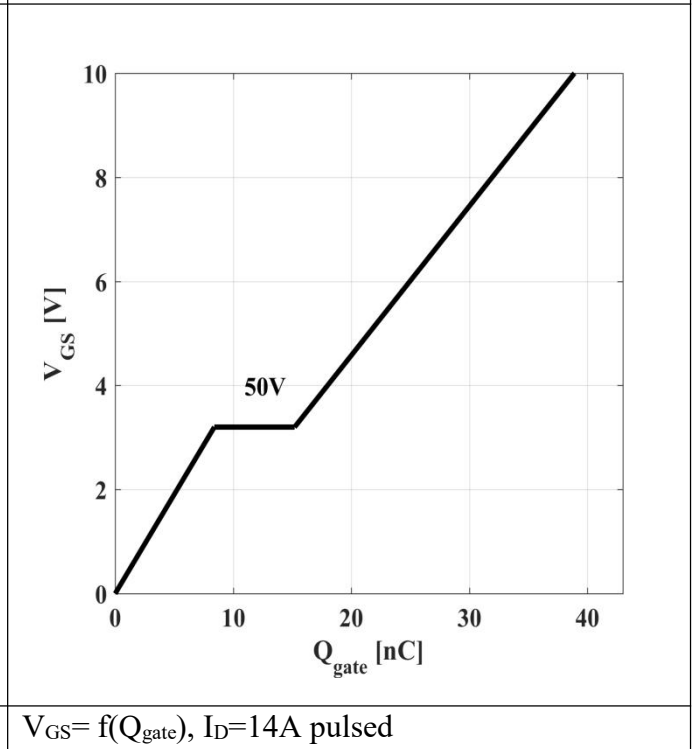
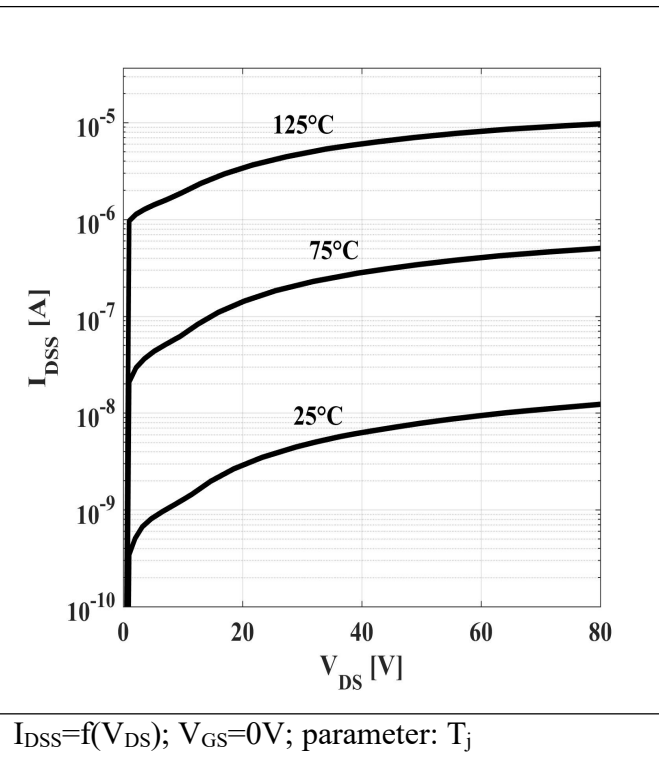
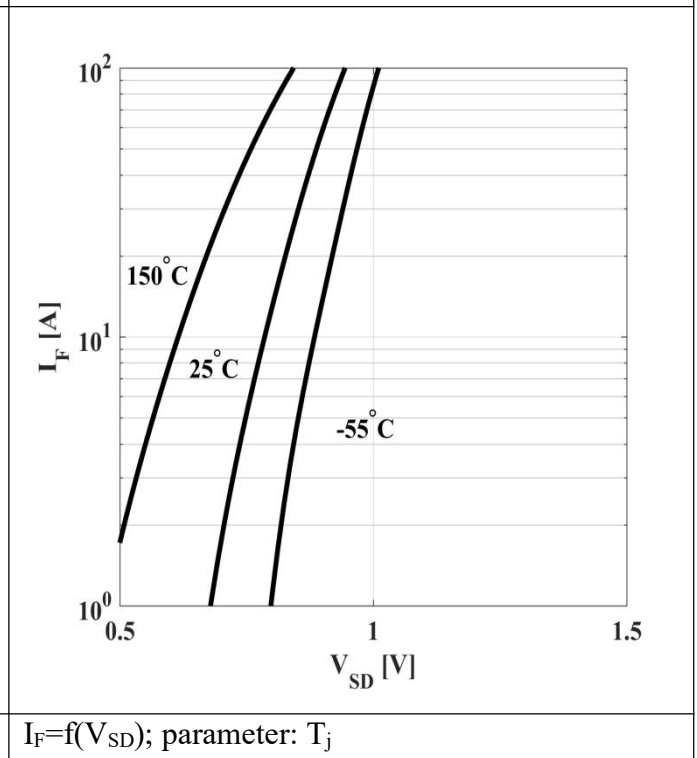
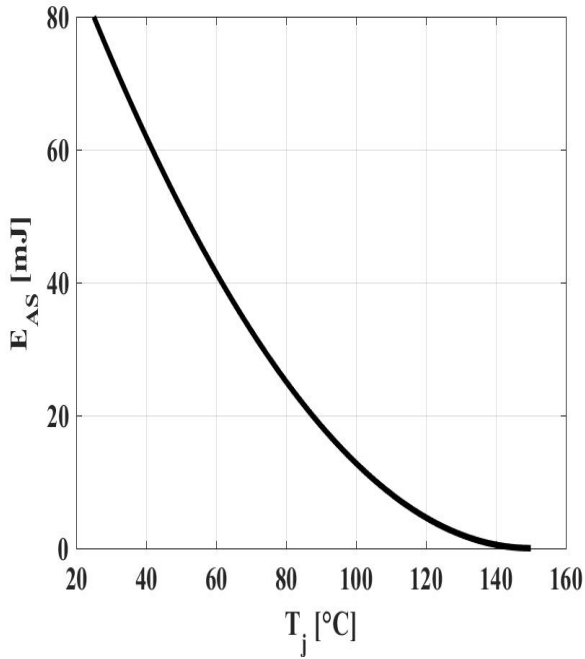
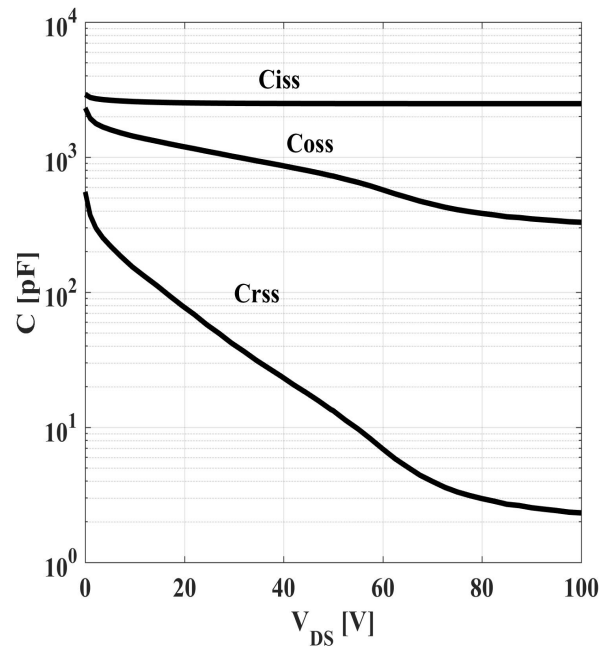
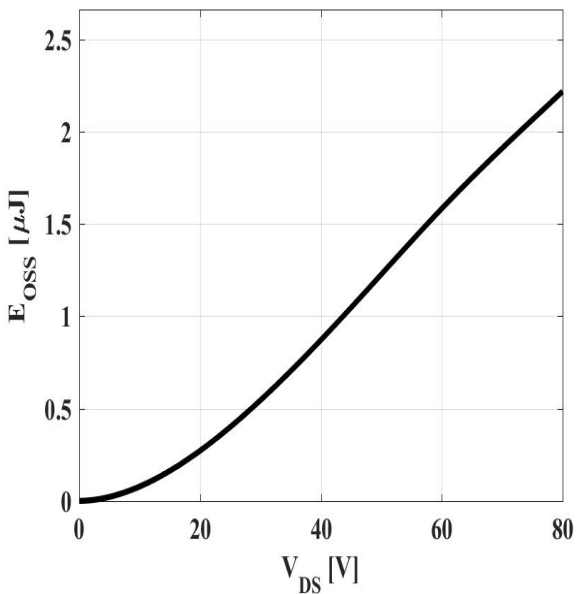
Figure 11: Typ. Gate Threshold Voltage

Figure 12: Typ. Gate Charge

Figure 13: Drain-Source Leakage Current

Figure 14: Forward Characteristics of Reverse Diode


Figure 15: Avalanche Energy


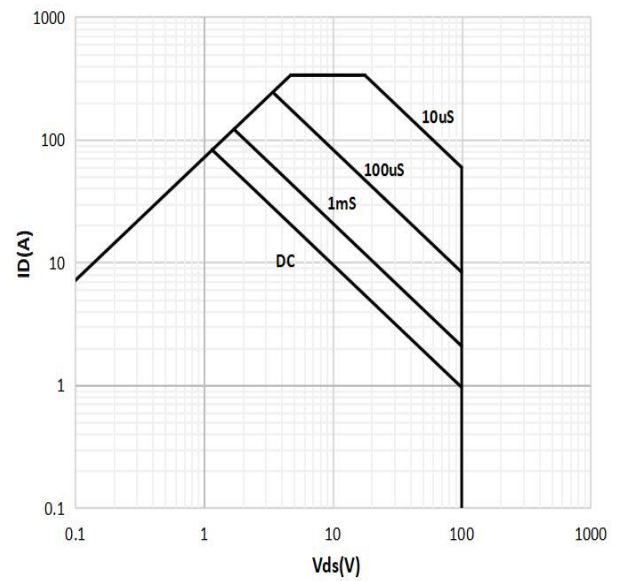
$$E_{AS}=f(T_j); I_D=14.0A; V_{DD}=50V$$

Figure 16: Typ. Capacitances


$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

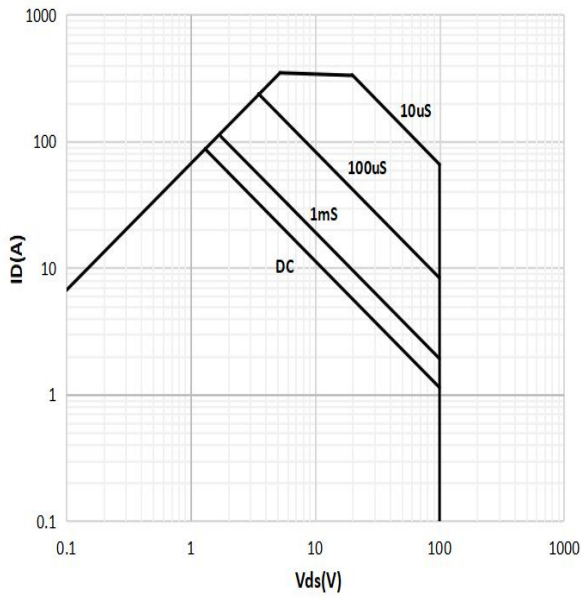
Figure 17: Coss Stored Energy


$$E_{OSS}=f(V_{DS})$$

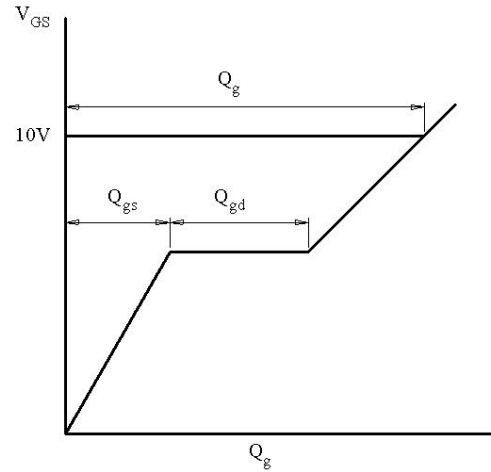
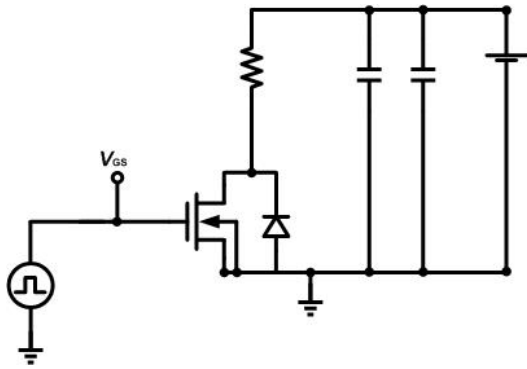
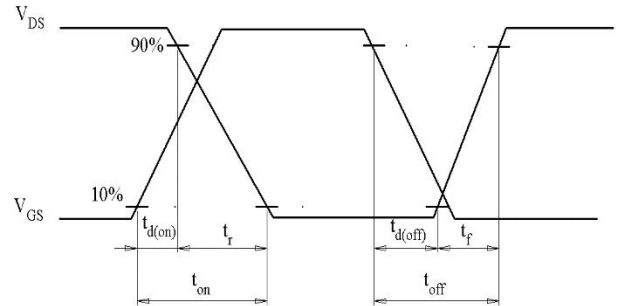
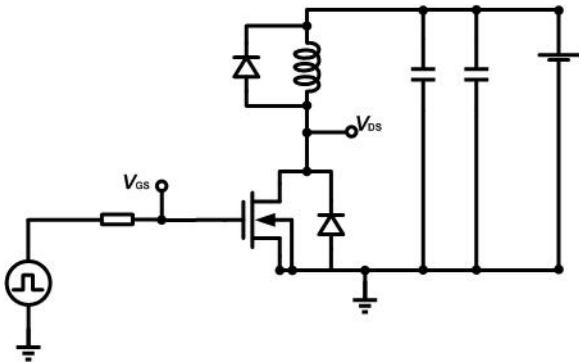
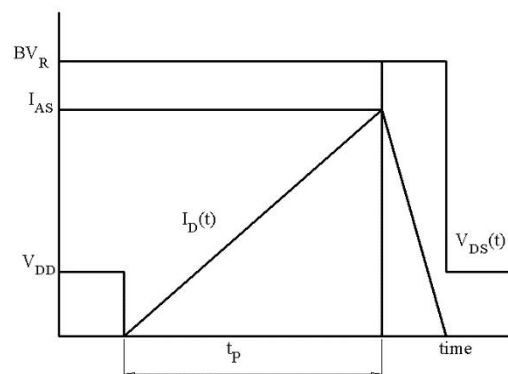
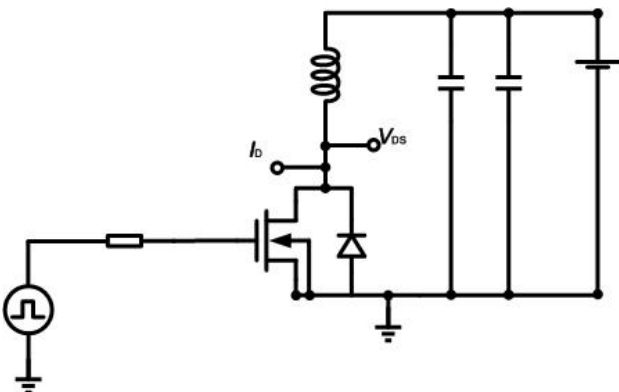
Figure 18A: Safe Operating Area(PDFN5*6)


$$I_D = f(V_{DS}); T_c = 25^\circ C; V_{GS} > 7V; \text{parameter } t_p$$

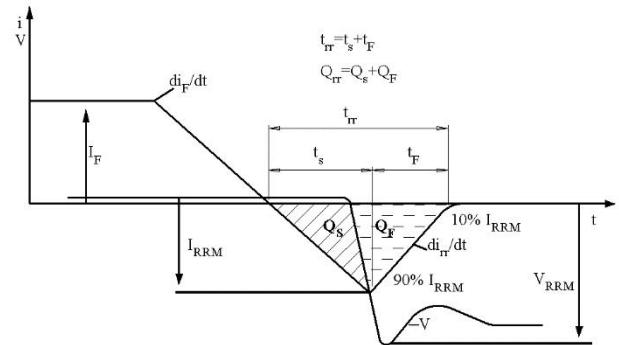
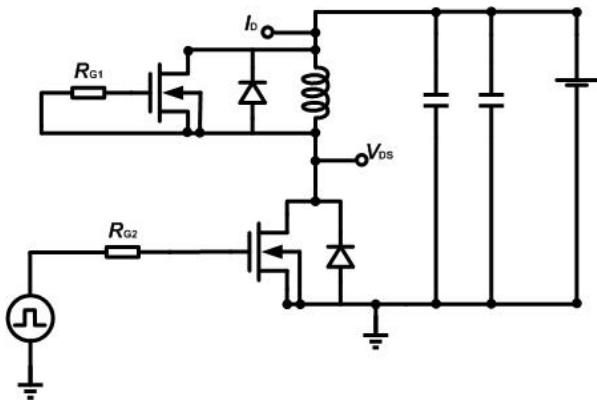
Figure 18B: Safe Operating Area(TO-220C)

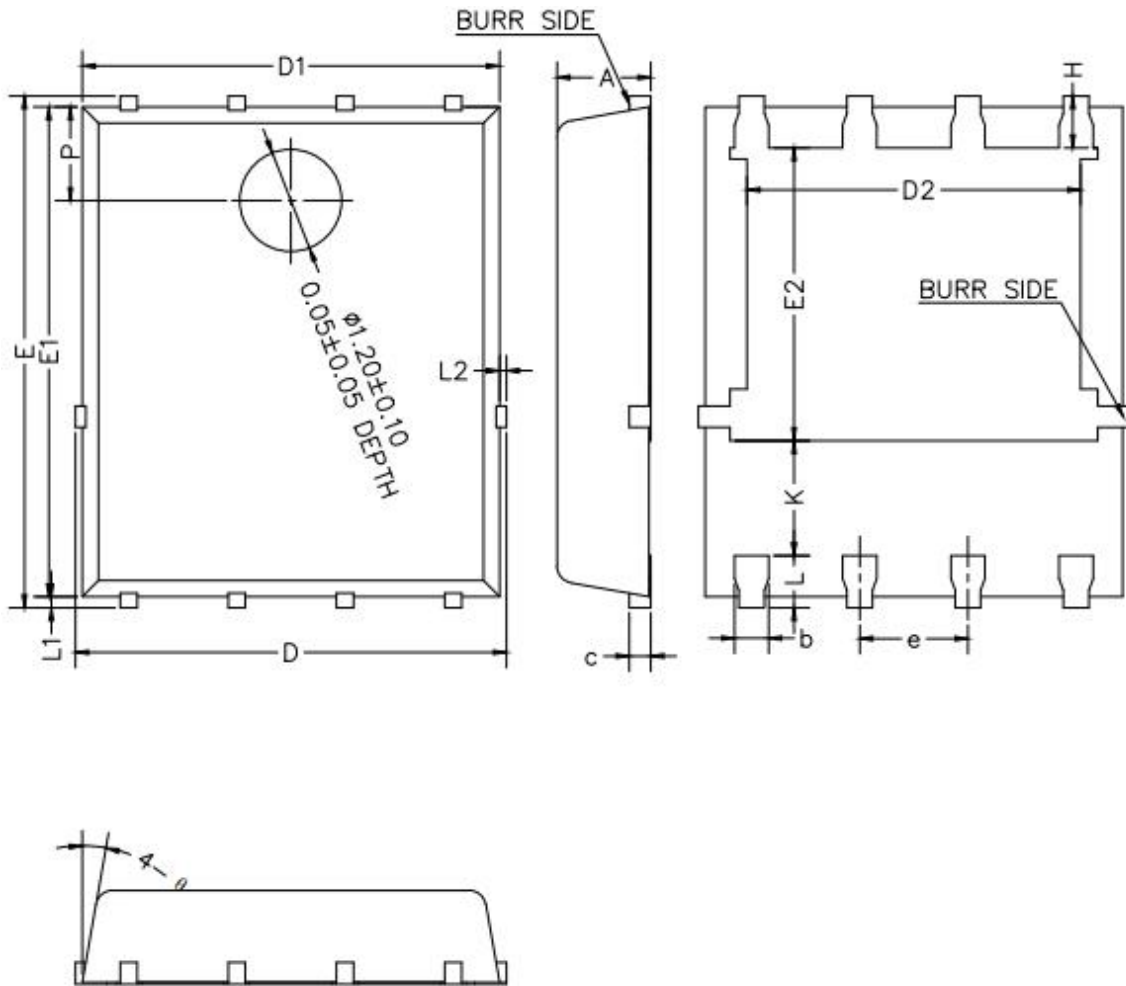


$I_D = f(V_{DS}); T_c = 25^\circ\text{C}; V_{GS} > 7\text{V};$ parameter t_p

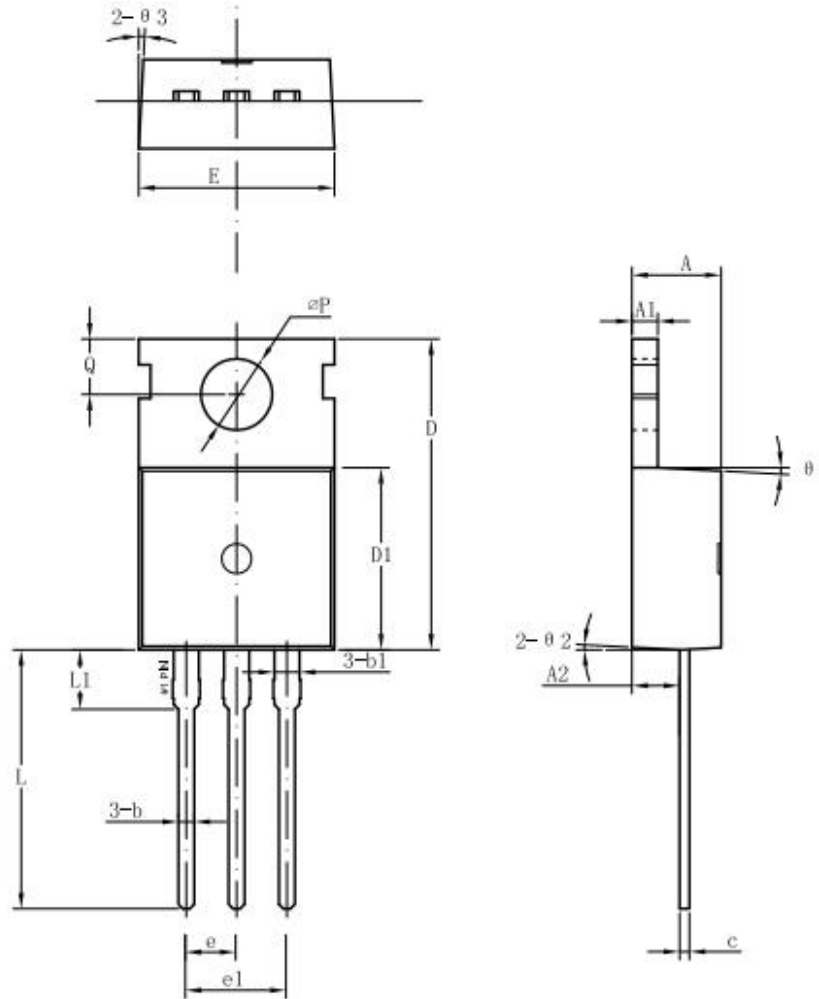
Test Circuits
1. Gate Charge Test Circuit & Waveform

2. Switch Time Test Circuit

3. Unclamped Inductive Switching Test Circuit & Waveforms


4. Test Circuit and Waveform for Diode Characteristics



Mechanical Dimensions
DFN5*6-8 Unit: mm


Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.90	1.10	1.20	E2	3.18	-	3.54
b	0.35	0.40	0.45	H	0.51	0.61	0.71
c	0.21	0.25	0.34	K	1.10	-	-
D	-	-	5.10	L	0.51	0.61	0.71
D1	4.80	4.90	5.00	L1	0.06	0.13	0.20
D2	3.82	-	4.11	L2	-	-	0.10
e	1.17	1.27	1.37	P	1.00	1.10	1.20
E	5.90	6.00	6.10	θ	8°	10°	12°
E1	5.70	5.75	5.80				

Mechanical Dimensions
TO-220C(SRT10N022HTC-G/E)
Unit: mm


Symbol	Dimensions (mm)			Symbol	Dimensions (mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.30	4.50	4.70	e	-	2.54	-
A1	1.25	1.30	1.40	e1	-	5.08	-
A2	2.20	2.40	2.60	L	12.60	13.08	13.60
b	0.70	0.80	0.95	L1	-	3.00	-
b1	-	1.27	-	ΦP	3.50	3.60	3.80
c	0.40	0.50	0.65	Q	2.60	2.80	3.00
D	15.20	15.70	16.20	⊙1	-	3°	-
D1	9.00	9.20	9.40	⊙2	-	3°	-
E	9.70	10.00	10.10	⊙3	-	3°	-



Sanrise Technology Limited Company

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